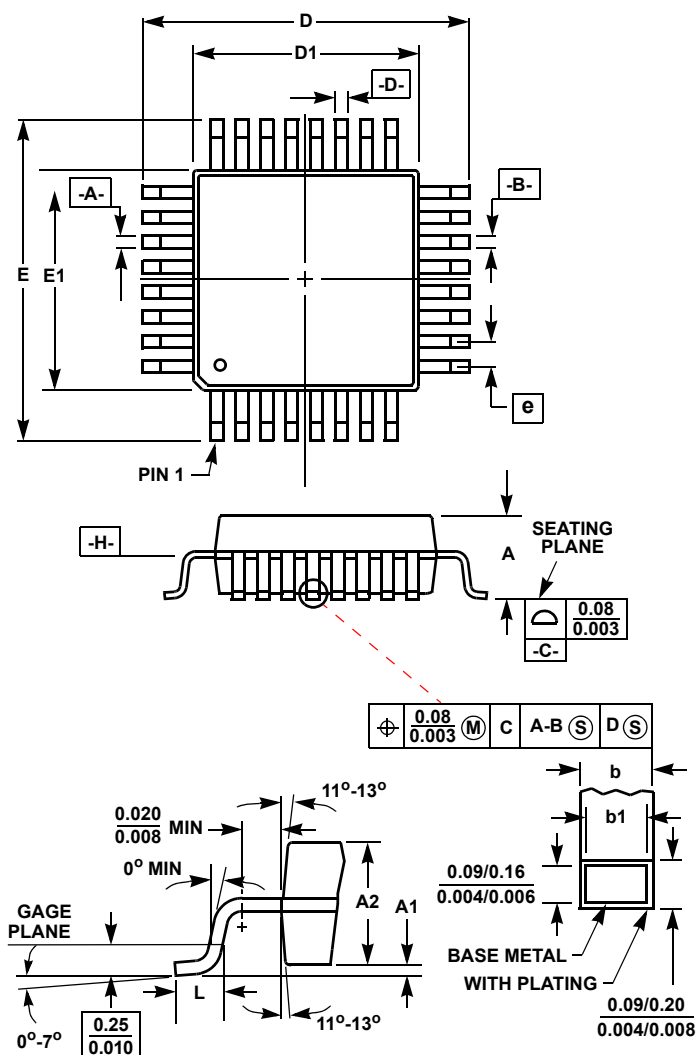


Plastic Packages for Integrated Circuits

Thin Plastic Quad Flatpack Packages (TQFP)

Q32.7x7 (JEDEC MS-026ABA ISSUE B) 32 LEAD THIN PLASTIC QUAD FLATPACK PACKAGE



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.047	-	1.20	-
A1	0.002	0.005	0.05	0.15	-
A2	0.038	0.041	0.95	1.05	-
b	0.012	0.018	0.30	0.45	6
b1	0.012	0.016	0.30	0.40	-
D	0.350	0.358	8.90	9.10	3
D1	0.272	0.280	6.90	7.10	4, 5
E	0.350	0.358	8.90	9.10	3
E1	0.272	0.280	6.90	7.10	4, 5
L	0.018	0.029	0.45	0.75	-
N	32		32		7
e	0.031 BSC		0.80 BSC		-

Rev. 0 10/06

NOTES:

- Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.
- All dimensions and tolerances per ANSI Y14.5M-1982.
- Dimensions D and E to be determined at seating plane -C-.
- Dimensions D1 and E1 to be determined at datum plane -H-.
- Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm (0.010 inch) per side.
- Dimension b does not include dambar protrusion. Allowable dambar protrusion shall not cause the lead width to exceed the maximum b dimension by more than 0.08mm (0.003 inch).
- "N" is the number of terminal positions.